

**REMARKS**

Favorable reconsideration of this application is requested in view of the above amendments and the following remarks. Claim 10 has been amended editorially, and as supported by paragraphs [0031]-[0032] of the specification and Figs. 4, 5, 6A, 6C and 6D. No new matter is added. Claim 10 is pending.

***Claim Rejections - 35 USC § 103***

Claim 10 has been rejected under 35 U.S.C. 103(a) as unpatentable over either Akira et al. (JP 09-197394) in view of Frederick (U.S. Patent No. 4,373,611), Mizutani et al. (U.S. Patent No. 6,258,666) and Mizuno et al. (U.S. Patent No. 5,466,325). Applicants respectfully traverse this rejection.

Claim 10 is directed to a film peeling method for a display panel that requires, among other features, the step of rotating the roller and at the same time moving the transport pallet on which the display panel is mounted by use of the transport system so as to peel off the film on the surface of the display panel.

The combination of Akira, Frederick, Mizutani and Mizuno does not teach or suggest these features. Akira is directed to a device for peeling a polarizing plate from a liquid crystal panel. As it would be understood from the paragraph [0021] of the Akira, the liquid crystal panel (2) is conveyed by rotation of the motor (5) for the rolling-up. Accordingly, Akira is silent with respect to the step of rotating the roller and at the same time moving the transport pallet.

Frederick is directed to a system for a grocery store which includes an unloading conveyor and a grocery cart. Mizutani is directed to a method of peeling a semiconductor thin film and a method of producing a solar cell using the semiconductor thin film. Mizuno is directed to a resist removing method that comprises steps of adhering an adhesive tape onto a surface of a resist pattern formed on a semiconductor wafer and peeling off the resist pattern together with the adhesive tape. Nowhere do these references suggest the step as discussed above and none of these references remedies the deficiency of Akira. With regard to Mizuno, the resist pattern (4) on the semiconductor wafer (1) is peeled off after strengthening of the adhesion between the adhesive tape (6) and the resist pattern (4) by an adhesion strengthening means (7) such as a lamp or a

heater. However, the peeling of the resist pattern (4) is not due to the movement of the wafer-transporting belt (2), but to winding of the adhesive tape (6) by the winding reel (9) in this reference. It is apparent that the resist pattern (4) can be peeled off even when the wafer-transporting belt (2) has been stopped, as long as the winding reel (9) is being driven for the winding the adhesive tape (6).

For at least these reasons, claim 10 is not unpatentable over the combination of Akira, Frederick, Mizutani and Mizuno.

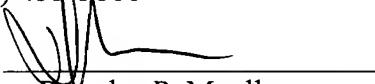
Applicants respectfully request that a timely Notice of Allowance be issued in this case. If the Examiner believes a telephone conference would advance the prosecution of this application, the Examiner is invited to telephone the undersigned at the below-listed telephone number.



Dated: June 28, 2011

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